ABSTRACT OF THE DISCLOSURE

A multilayer-wiring substrate having a via hole structure and method for fabricating the same. Referring to Figs. 1(a) and 1(b), after a via-hole 5 is formed by exposure and development in lithography or by laser-drilling, a bottom portion of the via-hole 5 is subjected to resin-etching so as to expose a surface 4A of a lower conductor 4 as shown in Fig. 3(b). The exposed surface 4A of the lower conductor 4 is chemically etched so that the conductor 4 is undercut. As a result, undesired material 5B such as adhered residual resin shown in Fig. 3(b) is completely removed. In etching the conductor 4 at the bottom of the via hole 5, the lower conductor 4 is preferably etched in an amount of 5-30% of the thickness of the lower conductor 4 to form a depression or recess 6A at a via hole bottom 5C as shown in Fig. 3(b), thereby reliably establishing electrical continuity between the lower conductor 4 and the upper conductor 8 by means of a via-hole conductor 7 as shown in Fig. 3(c).